

Description

The STN4130 uses advanced trench technology

to provide excellent R_{DS(ON)}, low gate charge and

operation with gate voltages as low as 4.5V. This

device is suitable for use as a

Battery protection or in other Switching application.

General Features

V_{DS} = 60V I_D =20 A

 $R_{DS(ON)} < 32m\Omega @ V_{GS}=10V$

Application

Battery protection

Load switch

Uninterruptible power supply

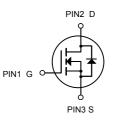
Package Marking and Ordering Information

Product ID	Pack	Brand	Qty(PCS)
STN4130	TO-252-2L	HXY MOSFET	2500

Absolute Maximum Ratings (Tc=25°Cunless otherwise noted)

Symbol	Parameter	Rating	Units
Vds	Drain-Source Voltage	rain-Source Voltage 60	
Vgs	Gate-Source Voltage	±20	V
I₀@Tc=25°C	Continuous Drain Current, V _{GS} @ 10V ¹	20	А
I₀@Tc=100°C	Continuous Drain Current, V _{GS} @ 10V ¹	10	А
Ідм	Pulsed Drain Current ²	80	A
EAS	Single Pulse Avalanche Energy ³	38	mJ
P _D @T _C =25°C	Total Power Dissipation ⁴	34.7	W
Тѕтс	Storage Temperature Range	Storage Temperature Range -55 to 150	
TJ	Operating Junction Temperature Range	-55 to 150	°C





N-Channel MOSFET



Electrical Characteristics (T_J = 25°C, unless otherwise noted)

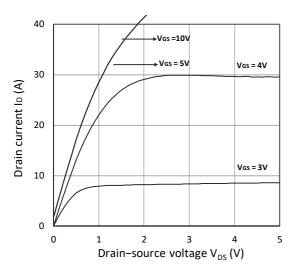
Parameter		Symbol	Test Conditions	Min.	Тур.	Max.	Unit
Static Characteristics		1	1		1	1	
Drain-Source Breakdown Vo	oltage	V _{(BR)DSS}	DSS V _{GS} = 0V, I _D = 250µA		-	-	V
Gate-Body Leakage Curren	t	lgss	$V_{DS} = 0V, V_{GS} = \pm 20V$	-	-	±100	nA
Zero Gate Voltage Drain Current	TJ=25℃	ldss	V _{DS} = 60V, V _{GS} = 0V	-	-	1	μA
	TJ=100℃			-	-	100	
Gate-Threshold Voltage		V _{GS(th)}	$V_{DS} = V_{GS}, I_D = 250 \mu A$	1.2	1.7	2.5	V
Drain-Source on-Resistance ⁴			V _{GS} = 10V, I _D = 10A	-	25	32	<u> </u>
		R _{DS(on)}	V _{GS} = 4.5V, I _D = 5A	-	31.5	40	mΩ
Forward Transconductance ⁴		g fs	V _{DS} = 5V, I _D = 10A	-	15.5	-	S
Dynamic Characteristic	S ⁵				L		
Input Capacitance		Ciss		-	1355	-	
Output Capacitance		C _{oss}	V _{DS} = 30V, V _{GS} =0V, f =1MHz	-	60	-	pF
Reverse Transfer Capacitance		Crss		-	49	-	
Gate Resistance		Rg	f =1MHz	-	1.2	-	Ω
Switching Characteristi	CS ⁵	·					•
Total Gate Charge		Qg		-	22	-	
Gate-Source Charge		Qgs	V _{GS} = 10V, V _{DD} = 30V, I _D = 10A	-	4.2	-	nC
Gate-Drain Charge		Q _{gd}		-	6.9	-	
Turn-on Delay Time		t _{d(on)}		-	6.4	-	-
Rise Time		tr	- V _{GS} =10V, V _{DD} = 30V,	-	15.3	-	
Turn-off Delay Time		t _{d(off)}	$R_G = 3\Omega, I_D = 10A$	-	25	-	ns
Fall Time		tr	-	-	7.6	-	
Body Diode Reverse Recov	ery Time	trr		-	26	-	ns
Body Diode Reverse Recovery Charge		Qrr	l⊧=10A, dl⊧/dt=100A/µs	-	45	-	nC
Drain-Source Body Dio	de Characte	ristics	1	I	L	1	1
Diode Forward Voltage ⁴		Vsd	I _S = 10A, V _{GS} = 0V	-	-	1.2	V
Continuous Source Current	Tc=25℃	ls	_		_	20	A

Notes:

- 1. Repetitive rating, pulse width limited by junction temperature $T_{J(\text{MAX})}\text{=}150^\circ\text{C}$
- 2. The EAS data shows Max. rating . The test condition is $V_{\text{DD}}\text{=}25V,\,V_{\text{GS}}\text{=}10V,\,L\text{=}0.4\text{mH},\,I_{\text{AS}}\text{=}14\text{A}$
- 3. The data tested by surface mounted on a 1 inch2 FR-4 board with 2OZ copper, The value in any given application depends on the user's specific board design.
- 4. The data tested by pulsed , pulse width \leq 300us , duty cycle \leq 2%.
- 5. This value is guaranteed by design hence it is not included in the production test.



Typical Characteristics





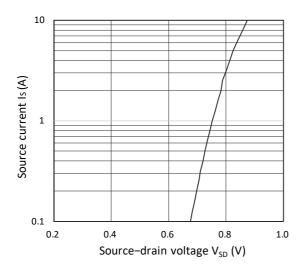


Figure 3. Forward Characteristics of Reverse

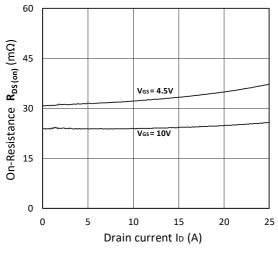


Figure 5. $R_{\text{DS}(\text{ON})}$ vs. I_{D}

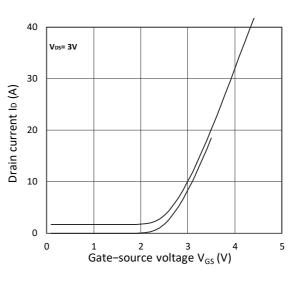


Figure 2. Transfer Characteristics

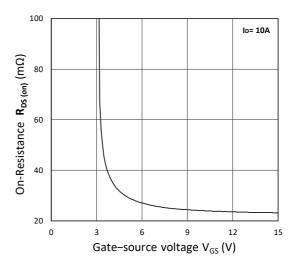


Figure 4. $R_{\text{DS}(\text{ON})}\,$ vs. V_{GS}

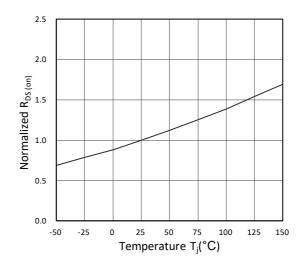
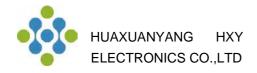


Figure 6. Normalized $R_{DS(on)}$ vs. Temperature



STN4130 N-Channel Enhancement Mode MOSFET

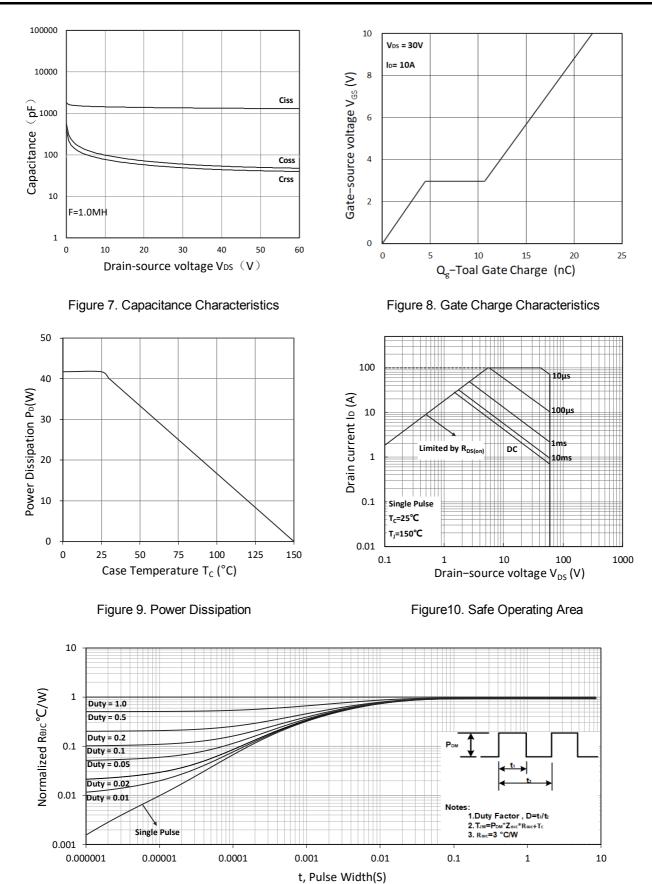
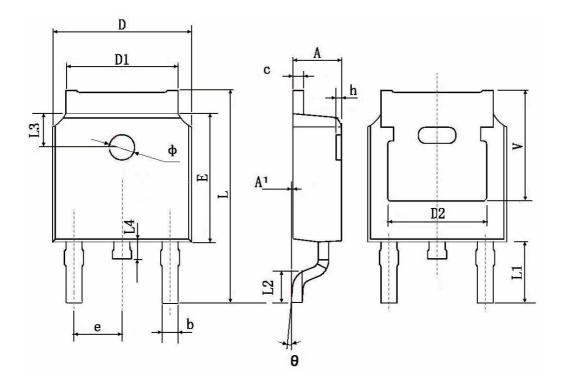


Figure 11. Normalized Maximum Transient Thermal Impedance



TO-252-2L Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches		
	Min.	Max.	Min.	Max.	
A	2.200	2.400	0.087	0.094	
A1	0.000	0.127	0.000	0.005	
b	0.660	0.860	0.026	0.034	
с	0.460	0.580	0.018	0.023	
D	6.500	6.700	0.256	0.264	
D1	5.100	5.460	0.201	0.215	
D2	0.483 TYP.		0.190 TYP.		
E	6.000	6.200	0.236	0.244	
е	2.186	2.386	0.086	0.094	
L	9.800	10.400	0.386	0.409	
L1	2.900 TYP.		0.114 TYP.		
L2	1.400	1.700	0.055	0.067	
L3	1.600 TYP.		0.063 TYP.		
L4	0.600	1.000	0.024	0.039	
Φ	1.100	1.300	0.043	0.051	
θ	0°	8°	0°	8°	
h	0.000	0.300	0.000	0.012	
V	5.350	5.350 TYP. 0.211 TYP.			



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